

AMENDMENTS TO THE CLAIMS**Listing of the Claims:**

Claims 1-36 (Cancelled)

Claims 37-52 (Cancelled)

53. (Cancelled)

54. (Cancelled)

55. (Previously presented) The liquid thermosetting ink-jet ink according to claim 68, wherein said curing agent is selected from a group consisting of urea derivatives, imidazoles, dicyandiamide, their precursors and/or any mixture thereof.

56. (Previously presented) The liquid thermosetting ink-jet ink according to claim 68, wherein said inert filler is selected from a group consisting of barium sulfate, talc, silica, kaolin, mica and glass.

57. (Cancelled).

58. (Currently amended) The liquid thermosetting ink-jet ink according to claim [[57]] 68, wherein the epoxy compounds resins are selected from group consisting of hydrogenated bisphenol S epoxy resins, heterocyclic epoxy resins, bisphenol A epoxy resins, hydrogenated bisphenol A epoxy resins, bisphenol F epoxy resins, Novolak epoxy resins, Novolak epoxy resins of bisphenol A, or a mixture thereof.

59. (Currently amended) The liquid thermosetting ink-jet ink according to claim [[53]] 68, additionally comprising monomers and/or oligomers selected from styrene, acrylic or methacrylic acid and esters thereof; acrylated or methacrylated epoxies; acrylated or methacrylated urethanes[;].

60. (Previously presented) The liquid thermosetting ink-jet ink according to claim 68, adapted for solder mask in printed circuit boards.

61. (Previously presented) The liquid thermosetting ink-jet ink according to claim 68, especially adapted for bonding devices or components in electronic manufacturing.

62. (Previously presented) The liquid thermosetting ink-jet ink according to claim 68, adapted for printing of layers in the manufacturing of passive component capacitors and/or resistors.

63. (Previously presented) The liquid thermosetting ink-jet ink according to claim 68, adapted for direct printing of conductive lines and features such as pads and/or bumps.

64. (Previously presented) The liquid thermosetting ink-jet ink according to claim 68, additionally comprising impact modifiers and/or flexibilizers having rubbery moieties or blocks in their chain.

65. (Currently amended) The liquid thermosetting ink-jet ink according to claim [[53]] 64, wherein the impact modifiers and/or flexibilizers are selected from amines, ~~epoxies~~ epoxy, hydroxyls, terminated rubbers or rubber-like compositions comprising polybutadienes, polyisoprenes, polysulfides, polyurethanes, hydrogenated polybutadienes and/or polyisoprenes, ethylene-propylene copolymers, soft polyacrylate esters, polydimethyl siloxane, zirconate, titanate, aluminate or any mixture thereof.

66. (Previously presented) The liquid thermosetting ink-jet ink according to claim 68, additionally comprising mineral fillers, having maximal particle size of about 2 micron in the final ink; wherein concentration ranges between about 1 to 30 % by weight.

67. (Previously presented) The liquid thermosetting ink-jet ink according to claim 68, additionally comprising additives selected from surface active agents and/or colloid stabilizers, rheology modifiers, pigments and dyes, matting agents, solvents; co-solvents, diluents or any mixture thereof.

68. (Previously presented) A micron liquid thermosetting ink-jet ink comprising:
- (a) at least one solid latent curing agent comprising an inert filler having maximal particle size of less than 2 microns; said curing agent is layered on the surface of said inert particle, deposited as crystals on its surface, impregnated in its porosity or dispersed in small crystals in a dispersing agent layer on or in the inert particle surface; and
  - (b) one or more epoxy resin;
- said ink-jet ink being characterized by a viscosity lower than 50 Cps at application temperature; a surface tension lower than 80 dyn/cm at application temperature; and a glass transition temperature, in the cured form, of greater than 120°C.